

ENABLING SUSTAINABLE PV PRODUCTION WITH LOW-TEMPERATURE SNAP CURABLE ELECTRICALLY CONDUCTIVE ADHESIVES

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AGENDA

01 Henkel at a glance

02 ECAs in Solar

03 Sustainability at Henkel



HENKEL - A COMPELLING **PORTFOLIO** WITH ICONIC BRANDS...

HENKEL GROUP

ADHESIVE TECHNOLOGIES



€3.3bn sales





€1.6bn sales



>75%

Sales share of our 5 brand clusters for industrial customers & 4 key brands for consumers

CONSUMER BRANDS











>50%
Top 10 brand sales share



SERVING **BROAD RANGE OF INDUSTRIES**ALONG THREE BUSINESS AREAS



MOBILITY & ELECTRONICS

Automotive OEMs & components, e-mobility, metal coil, electronics, semiconductor packaging, aerospace, industrial assembly, power & **Solar**

#1 WORLDWIDE



PACKAGING & CONSUMER GOODS

Food & beverage, hygiene, metal and flexible packaging, sports & fashion

#1 WORLDWIDE



& PROFESSIONAL

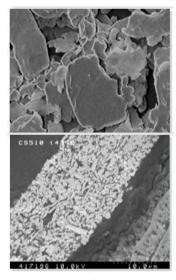
DIY, craftsmen, construction, engineered wood, professional users in manufacturing & maintenance

#3 WORLDWIDE



ELECTRICALLY CONDUCTIVE ADHESIVES (ECAS)

DEVELOPMENT OVERVIEW



Cross section of an ECA bond

ECA Technology

Conductive filler package

- Bulk and contact resistivity
- Current capacity
- Percolation threshold
- Rheology
- Reliability performance

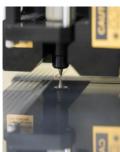
Polymer resin

- Cure speed
- Adhesion
- Reliability performance
- Work life

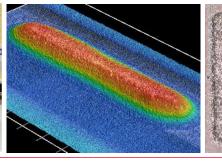
Interconnection type	Ribbon attach	Back contact
Cell type	c-Si, PERC, HJT	IBC, MWT
Products Qualified	CA 3556HF, ICP 8311 ICP 8282	3104WXL, 3103WLV , ICP 3535M2
Chemistry	Acrylate	Ероху

ECA application technique

- Printing: screen and stencil
- Dispensing
- Jetting
- → Focus on fast throughput







Developments on emerging technologies

Perovskite technology as a growing market

- Reduced thermal budget
- → Low temperature curing adhesives (optimally below 120 °C)

ECAs with improved non-noble compatibilities

Reduced total cost of ownership



ELECTRICALLY CONDUCTIVE ADHESIVES

VALUE PROPOSITION

Value Proposition



- Electrically conductive adhesives (ECAs) using advanced filler technology to minimize silver content and material density.
- ECAs containing anti-corrosion technology, enabling use of non-noble metallization.
- Flexible ECAs with low temperature cure profile reduces energy consumption in production



- Low temperature cure ECAs allow use of temperature sensitive components and substrates
- Low temperature and fast cure ECAs enable a reduced energy consumption footprint
- Improved H&S labeling (non CMR)
- Enabling higher module power, reduced Ag and usage -> more CO₂ savings



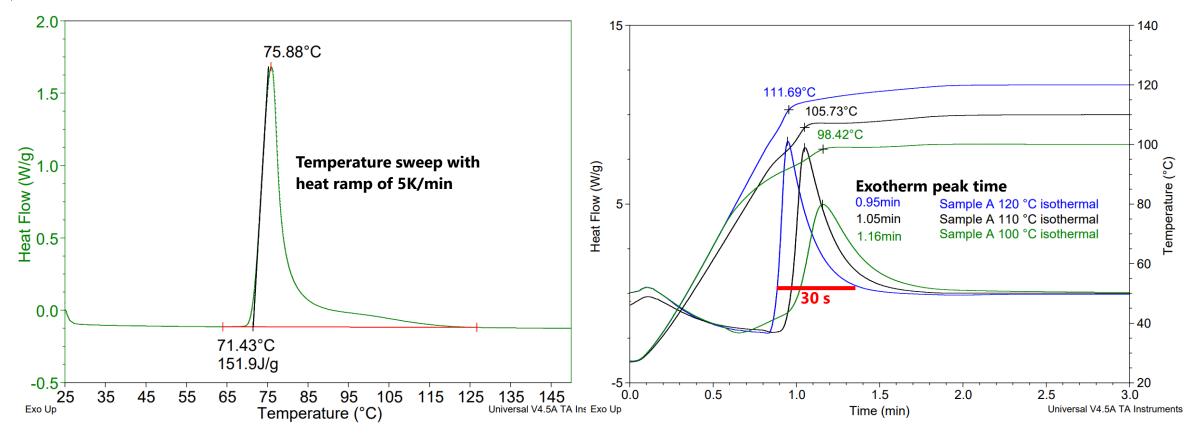
- ECAs that can cope with the increasing reliability demands from the industry
- ECAs with high current capabilities and heat dissipation
- ECAs with improved high temperature adhesion



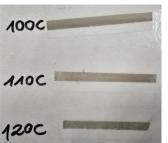
ECAs with focus on small feature/printing and high throughput.



CURE TIME EVALUATION OF ECAS



- Cure time evaluation via DSC → cure starts below 75 °C (left graph), full cure in 30s during 120 °C ramp (right graph)
- Glass slide samples exhibit surface tackiness after curing 30s at 120 °C on hot plate



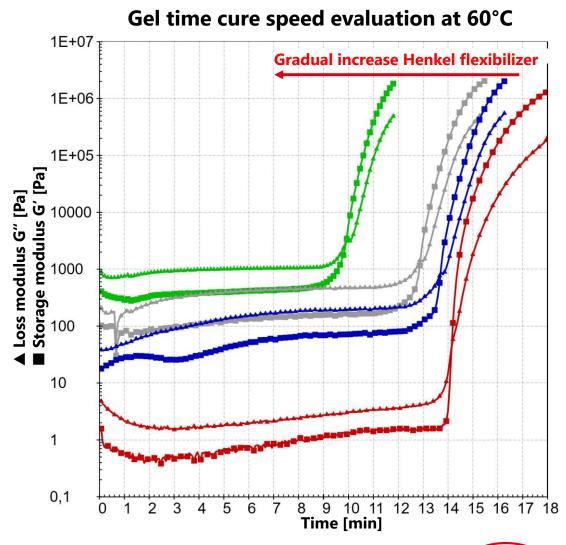


TACK-FREE ECA DEVELOPMENT

- Tack-free samples when curing under nitrogen atmosphere
 →surface oxygen inhibition
- Gel time as alternative to determine cure speed
- Development of oxygen scavenging flexibilizer (Henkel patent)
- Replacing standard flexibilizer results in reduced gel times, as well as reduction of tackiness



Tack-free samples after 20s at 120 °C





SUSTAINABILITY @HENKEL ADHESIVE TECHNOLOGIES

Leading by **EXAMPLE**

Leading through **TECHNOLOGY**

SUSTAINABLE OPERATIONS

19 carbon neutral plants & 96% Renewable Electricity

SBTi Net Zero Target 2045 (incl. Scope 3)

SUSTAINABLE PRODUCTS

Supporting suppliers to reduce process emissions (e.g. Recycled silvers)

ENABLING SUSTAINABILITY



LOWERING EMISSIONS IN CUSTOMER PROCESSES & PRODUCT USE PHASE



ENABLING REUSE, REPAIR & REFURBISH



ENHANCING SAFETY AT CUSTOMER PROCESSES



REDUCING WATER & IMPROVING WASTEWATER OUALITY

SUSTAINABILITY INTELLIGENCE

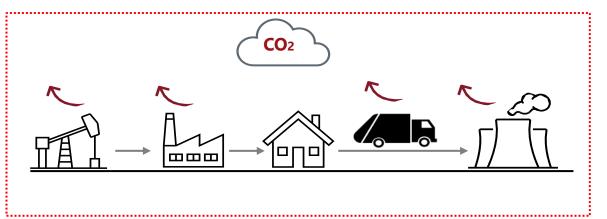
Providing transparency on our product carbon footprint





ECA GRADLE-TO-GATE CASE STUDY

- 1) Full silver, low silver and new filler technology
- 2) Curing schedules
- 3) Volume savings through density







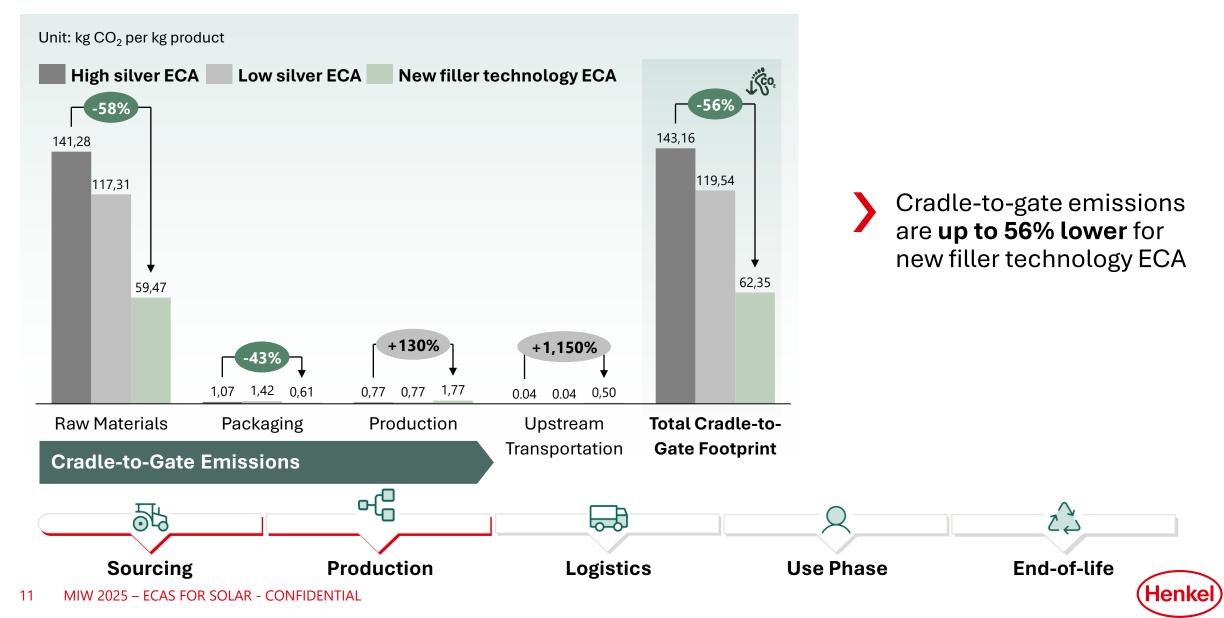




- 3. Functional Unit (FU): 1 kg
- Scenario 1: Full silver ECA (high silver loading 85 wt% Ag)
- Scenario 2: Low silver ECA (50-55 wt% Ag)
- Scenario 3: New Filler technology ECA (25-35 wt% Ag)
- 4. System Boundaries: Cradle-to-Gate and Downstream transportation
- Formulation
- Production technologies
- Packaging
- Upstream transportation
- Downstream transportation
- **5. Impact categories:** GWP100 [kg CO2-eq]
- 6. Geographic boundaries: Global Market
- 7. Emission factor data sources: BF 2.0/ Supplier values/ Ecoinvent 3.10
- 8. Standard: ISO 14040-44
- 9. Analysis tool: Internal Analysis, EF 3.1



EMISSIONS SAVINGS: CRADLE-TO-GATE



THANK YOU!

